

REMARKS

At the outset, the Examiner is thanked for the thorough review and consideration of the pending application. The Office Action dated September 20, 2006, has been received and its contents carefully reviewed.

By this Amendment, Applicant have amended claims 1, 13, 14 and 23. Accordingly, claims 1-23 remain pending in this application. Reexamination and reconsideration of the pending claims is respectfully requested.

In the Office Action, claims 1 and 14 are rejected under 35 U.S.C. § 112, second paragraph, allegedly because the scopes of claims 1 and 14 are not commensurate with the bodies of claims 1 and 14. Although Applicant respectfully disagrees with the Examiner, for the sole purpose of expediting the prosecution of the present application, claims 1 and 14 are amended.

In addition, claims 1-23 are rejected under 35 U.S.C. § 112, second paragraph, because of the term “curing” or “cured”. This rejection is respectfully traversed and reconsideration is requested.

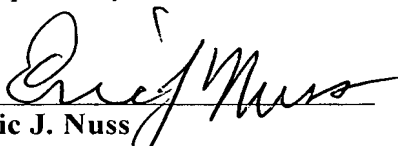
Applicant respectfully submits that it is known in the semiconductor art that a curing process stabilizes and improves the electrical characteristics of a silicon layer. It is believed that such improved electrical characteristics are caused by controlling the dangling bonds and traps of the silicon layer. Curing is generally performed in an air, inert, or hydrogen gas atmosphere. The present application at paragraphs [0062]-[0064] discloses that “the step of curing the polycrystalline silicon layer 403a etched to a predetermined thickness is performed so as to cure the injured region of the surface of the polycrystalline silicon layer 403a. Either an annealing process using a furnace or an annealing process using a laser may be used as a curing process. Also a rapid thermal annealing (RTA) may be used as the curing process...[t]hrough the processes, the injured silicon on the etched polycrystalline silicon layer 403a is cured along a good quality crystal formed on a lower portion of the polycrystalline silicon layer 403a.” Accordingly, Applicant respectfully submits that in light of the disclosures of the present application, claims 1-23 set out the subject matter of the present application with a reasonable degree of clarity and particularity to one of ordinary skill in the art. See MPEP 2173.02.

Applicant believes the application is in condition for allowance and early, favorable action is respectfully solicited. If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is requested to call the undersigned attorney at (202) 496-7500 to discuss the steps necessary for placing the application in condition for allowance. All correspondence should continue to be sent to the below-listed address.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. § 1.136, and any additional fees required under 37 C.F.R. § 1.136 for any necessary extension of time, or any other fees required to complete the filing of this response, may be charged to Deposit Account No. 50-0911. Please credit any overpayment to deposit Account No. 50-0911. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

Dated: December 20, 2006

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